

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming-Tsung Lee</td> <td>12/20/2011</td> </tr> <tr> <td>Cheng-Hua Yang</td> <td>12/20/2011</td> </tr> <tr> <td>Wen-Fang Lee</td> <td>12/20/2011</td> </tr> <tr> <td>Chih-Chung Wang</td> <td>12/20/2011</td> </tr> <tr> <td>Chih-Wei Hsu</td> <td>12/20/2011</td> </tr> <tr> <td>Po-Ching Chuang</td> <td>12/20/2011</td> </tr> </tbody> </table>		Name	Execution Date	Ming-Tsung Lee	12/20/2011	Cheng-Hua Yang	12/20/2011	Wen-Fang Lee	12/20/2011	Chih-Chung Wang	12/20/2011	Chih-Wei Hsu	12/20/2011	Po-Ching Chuang	12/20/2011
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<table border="1"> <tr> <td>Name:</td> <td>UNITED MICROELECTRONICS CORP.</td> </tr> <tr> <td>Street Address:</td> <td>No.3, Li-Hsin Road 2, Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu City</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	UNITED MICROELECTRONICS CORP.	Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park	City:	Hsin-Chu City	State/Country:	TAIWAN						
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PROPERTY NUMBERS Total: 1															
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CORRESPONDENCE DATA															
<p>Fax Number: (703)997-4517</p> <p>Phone: 3027291562</p> <p>Email: Patent.admin.uspto.cr@naipo.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: WINSTON HSU</p> <p>Address Line 1: P.O.BOX 506</p> <p>Address Line 4: Merrifield, VIRGINIA 22116</p>															
ATTORNEY DOCKET NUMBER:	NAUP1440USA														
NAME OF SUBMITTER:	SIBYL YU														

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Total Attachments: 4

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**PATENT**

**REEL: 027779 FRAME: 0178**

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Ming-Tsung Lee Nationality: TW

Name: Cheng-Hua Yang Nationality: TW

Name: Wen-Fang Lee Nationality: TW

Name: Chih-Chung Wang Nationality: TW

Name: Chih-Wei Hsu Nationality: TW

Name: Po-Ching Chuang Nationality: TW

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"HIGH VOLTAGE METAL-OXIDE-SEMICONDUCTOR TRANSISTOR DEVICE AND LAYOUT PATTERN THEREOF"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_
- (e) \_\_\_\_\_ International application no. \_\_\_\_\_

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this Dec. 20, 2011 (Date of signing). (請於明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Ming-Tsung Lee

Ming-Tsung Lee

Cheng-Hua Yang

Cheng-Hua Yang

Wen-Fang Lee

Wen-Fang Lee

Chih-Chung Wang

Chih-Chung Wang

Chih-Wei Hsu

Chih-Wei Hsu

Po-Ching Chuang

Po-Ching Chuang

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NPO#NAU-P1440-USA:0  
CUST#UMCD-2011-0456

*Assignment, Page 4 of 4*

F#NPO-P0002E-US1  
DSC0-100U016959

**RECORDED: 02/28/2012**

**PATENT**  
**REEL: 027779 FRAME: 0182**